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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16К х 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj256gp206at-i-mr

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong





2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including MCUs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μ F to 47 μ F.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 μ F and 10 μ F, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 24.0** "**Electrical Characteristics**" for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 21.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The $\overline{\text{MCLR}}$ pin provides for two specific device functions:

- Device Reset
- · Device programming and debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the \overline{MCLR} pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.



TABLE 4-2: CHANGE NOTIFICATION REGISTER MAP FOR PIC24HJXXXGPX10A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062		—	_	—	_	_	_	—	CN23IE	CN22IE	CN21IE	CN20IE	CN19IE	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	_	-	—	_	_	_	_	_	CN23PUE	CN22PUE	CN21PUE	CN20PUE	CN19PUE	CN18PUE	CN17PUE	CN16PUE	0000
			_				_											

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-3: CHANGE NOTIFICATION REGISTER MAP FOR PIC24HJXXXGPX08A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	—	—	_		—	_	_	_	—	_	CN21IE	CN20IE	CN19IE	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	_	_	_	_	_	_	-		_	_	CN21PUE	CN20PUE	CN19PUE	CN18PUE	CN17PUE	CN16PUE	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-4: CHANGE NOTIFICATION REGISTER MAP FOR PIC24HJXXXGPX06A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	_	_	_	_	_	_	_	_		_	CN21IE	CN20IE	_	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	_	_	_	_	_	_	_	_		_	CN21PUE	CN20PUE	_	CN18PUE	CN17PUE	CN16PUE	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1RS	0180							Ou	tput Compar	e 1 Second	ary Register							xxxx
OC1R	0182								Output Co	ompare 1 Re	egister							xxxx
OC1CON	0184	—	_	OCSIDL	—	—	_	_	_	_	_	_	OCFLT	OCTSEL		OCM<2:0>		0000
OC2RS	0186							Ou	tput Compar	e 2 Second	ary Register							xxxx
OC2R	0188								Output Co	ompare 2 Re	egister							xxxx
OC2CON	018A	_	_	OCSIDL	_	_	_	_	_	_	_	_	OCFLT	OCTSEL		OCM<2:0>		0000
OC3RS	018C							Ou	tput Compar	e 3 Second	ary Register							xxxx
OC3R	018E								Output Co	ompare 3 Re	egister							xxxx
OC3CON	0190	_	_	OCSIDL	_	_	_	_	_	_	_	_	OCFLT	OCTSEL		OCM<2:0>		0000
OC4RS	0192							Ou	tput Compar	e 4 Second	ary Register							XXXX
OC4R	0194								Output Co	ompare 4 Re	egister							XXXX
OC4CON	0196	_	—	OCSIDL	—	—	_	_	_	_	—	—	OCFLT	OCTSEL		OCM<2:0>		0000
OC5RS	0198							Ou	tput Compar	e 5 Second	ary Register							xxxx
OC5R	019A								Output Co	ompare 5 Re	egister							xxxx
OC5CON	019C		—	OCSIDL	—	—	_	—		_	—	—	OCFLT	OCTSEL		OCM<2:0>		0000
OC6RS	019E							Ou	tput Compar	e 6 Second	ary Register							xxxx
OC6R	01A0								Output Co	ompare 6 Re	egister							xxxx
OC6CON	01A2	_	_	OCSIDL	_	_	_	_		_	_	_	OCFLT	OCTSEL		OCM<2:0>		0000
OC7RS	01A4							Ou	tput Compar	e 7 Second	ary Register							xxxx
OC7R	01A6								Output Co	ompare 7 Re	egister							xxxx
OC7CON	01A8		—	OCSIDL	—	—	_	—		_	—	—	OCFLT	OCTSEL		OCM<2:0>		0000
OC8RS	01AA							Ou	tput Compar	e 8 Second	ary Register							xxxx
OC8R	01AC								Output Co	ompare 8 Re	egister							xxxx
OC8CON	01AE	_	_	OCSIDL	_	_		_			_	_	OCFLT	OCTSEL		OCM<2:0>		0000
1 1						1 (-1					D							

TABLE 4-8: OUTPUT COMPARE REGISTER MAP

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-9: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1RCV	0200	_	—	—	_	-	_	—	—				Receive	Register				0000
I2C1TRN	0202	_	_	_	_	_	_	_	_				Transmit	Register				OOFF
I2C1BRG	0204	_	_	_	_	_	_	_				Baud Rat	e Generato	r Register				0000
I2C1CON	0206	I2CEN		I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1STAT	0208	ACKSTAT	TRSTAT	_	_	_	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	Р	S	R_W	RBF	TBF	0000
I2C1ADD	020A	_	_	_	_	_	_					Address	Register					0000
I2C1MSK	020C	_	_	_	_	_	_			Address Mask Register								0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-10: I2C2 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C2RCV	0210	_	_	_	_	_		—	_				Receive	Register				0000
I2C2TRN	0212	_	_	_	_	_	_	_	_				Transmit	Register				00FF
I2C2BRG	0214	_	_	_	_	_	_	_		Baud Rate Generator Register							0000	
I2C2CON	0216	I2CEN	_	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C2STAT	0218	ACKSTAT	TRSTAT	_	_	_	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	Р	S	R_W	RBF	TBF	0000
I2C2ADD	021A	—	—	_	_					Address Register								0000
I2C2MSK	021C	_	_	_	_	_	_			Address Mask Register								0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-11: UART1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
U1MODE	0220	UARTEN	—	USIDL	IREN	RTSMD	—	UEN1	UEN0	WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSE	L<1:0>	STSEL	0000
U1STA	0222	UTXISEL1	UTXINV	UTXISEL0	_	UTXBRK	UTXEN	UTXBF	TRMT	URXIS	EL<1:0>	ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
U1TXREG	0224	_	_	_	_	_	_	_				UART	Transmit Re	gister				xxxx
U1RXREG	0226	_	_	_	_	_	_	_				UART	Receive Re	gister				0000
U1BRG	0228							Bau	d Rate Ger	nerator Presc	aler							0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-31: SYSTEM CONTROL REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	-	—	—	—	—	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	xxxx(1)
OSCCON	0742	_	(COSC<2:0	>	_	I	NOSC<2:0	>	CLKLOCK	—	LOCK	_	CF	_	LPOSCEN	OSWEN	₀₃₀₀ (2)
CLKDIV	0744	ROI		DOZE<2:0	>	DOZEN	F	RCDIV<2:0)>	PLLPOS	ST<1:0>				PLLPRE<4	:0>		3040
PLLFBD	0746	_	_	_	_	_	_	_					PLLDIV<8:	0>				0030
OSCTUN	0748	_	_	_	_	_	_	_	_	_	_			TUT	<5:0>			0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

Note 1: RCON register Reset values dependent on type of Reset.

2: OSCCON register Reset values dependent on the FOSC Configuration bits and by type of Reset.

TABLE 4-32: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	—	-	—	_	—	_	ERASE	_	_		NVMO	P<3:0>		0000(1)
NVMKEY	0766	_	_	_	—		—	_	—				NVMKE	Y<7:0>				0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-33: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	C2MD	C1MD	AD1MD	0000
PMD2	0772	IC8MD	IC7MD	IC6MD	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	OC8MD	OC7MD	OC6MD	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0774	T9MD	T8MD	T7MD	T6MD	_	_	_	_	_	_	_	_	_	_	I2C2MD	AD2MD	0000

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

PIC24HJXXXGPX06A/X08A/X10A

FIGURE 8-1: TOP LEVEL SYSTEM ARCHITECTURE USING A DEDICATED TRANSACTION BUS Peripheral Indirect Address **DMA Controller** DMA 1 Ready DMA Control DMA I DMA RAM SRAM Peripheral 3 Channels I 1 PORT 1 PORT 2 Т CPU DMA 1 SRAM X-Bus DMA DS Bus CPU Peripheral DS Bus CPU DMA CPU DMA Non-DMA DMA DMA CPU Ready Ready Ready Peripheral Peripheral 2 Peripheral 1 Note: CPU and DMA address buses are not shown for clarity.

8.1 DMAC Registers

Each DMAC Channel x (x = 0, 1, 2, 3, 4, 5, 6 or 7) contains the following registers:

- A 16-bit DMA Channel Control register (DMAxCON)
- A 16-bit DMA Channel IRQ Select register (DMAxREQ)
- A 16-bit DMA RAM Primary Start Address Offset register (DMAxSTA)
- A 16-bit DMA RAM Secondary Start Address Offset register (DMAxSTB)
- A 16-bit DMA Peripheral Address register (DMAxPAD)
- A 10-bit DMA Transfer Count register (DMAxCNT)

An additional pair of status registers, DMACS0 and DMACS1 are common to all DMAC channels.

PIC24HJXXXGPX06A/X08A/X10A

EQUATION 9-3:

XT WITH PLL MODE

= 40 MIPS

EXAMPLE

 $FCY = \frac{FOSC}{2} = \frac{1}{2} \left(\frac{10000000 \cdot 32}{2 \cdot 2} \right)$

For example, suppose a 10 MHz crystal is being used, with "XT with PLL" being the selected oscillator mode. If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz. If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 x 32 = 160 MHz, which is within the 100-200 MHz ranged needed.

If PLLPOST<1:0> = 0, then N2 = 2. This provides a Fosc of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

FIGURE 9-2: PIC24HJXXXGPX06A/X08A/X10A PLL BLOCK DIAGRAM



TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	1, 2
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	xx	101	1
Secondary (Timer1) Oscillator (Sosc)	Secondary	xx	100	1
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	—
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	1
Primary Oscillator (HS)	Primary	10	010	-
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	1
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	1
Fast RC Oscillator (FRC)	Internal	xx	000	1

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5	ACKDT: Acknowledge Data bit (when operating as I ² C master, applicable during master receive) Value that will be transmitted when the software initiates an Acknowledge sequence. 1 = Send NACK during Acknowledge 0 = Send ACK during Acknowledge
bit 4	 ACKEN: Acknowledge Sequence Enable bit (when operating as I²C master, applicable during master receive) 1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence. 0 = Acknowledge sequence not in progress
bit 3	RCEN: Receive Enable bit (when operating as I ² C master) 1 = Enables Receive mode for I ² C. Hardware clear at end of eighth bit of master receive data byte. 0 = Receive sequence not in progress
bit 2	 PEN: Stop Condition Enable bit (when operating as I²C master) 1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence. 0 = Stop condition not in progress
bit 1	 RSEN: Repeated Start Condition Enable bit (when operating as I²C master) 1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence. 0 = Repeated Start condition not in progress
bit 0	 SEN: Start Condition Enable bit (when operating as I²C master) 1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence. 0 = Start condition not in progress

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3	 Start bit 1 = Indicates that a Start (or Repeated Start) bit has been detected last 0 = Start bit was not detected last
bit 2	Hardware set or clear when Start, Repeated Start or Stop detected. R_W: Read/Write Information bit (when operating as I^2C slave) 1 = Read – indicates data transfer is output from slave
	0 = Write - indicates data transfer is input to slaveHardware set or clear after reception of I2C device address byte.
bit 1	RBF: Receive Buffer Full Status bit
	 1 = Receive complete, I2CxRCV is full 0 = Receive not complete, I2CxRCV is empty Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.
bit 0	TBF: Transmit Buffer Full Status bit
	 1 = Transmit in progress, I2CxTRN is full 0 = Transmit complete, I2CxTRN is empty Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

REGISTER 17-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	_	—	—	—	—	AMSK9	AMSK8
bit 15					•		bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7					•		bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'	

-n = Value at POR (1' = Bit is set (0' = Bit is cleared x = Bit is unknown)

bit 15-10 Unimplemented: Read as '0'

bit 9-0

AMSKx: Mask for Address Bit x Select bit

1 = Enable masking for bit x of incoming message address; bit match not required in this position

0 = Disable masking for bit x; bit match required in this position

18.1 UART Helpful Tips

- 1. In multi-node direct-connect UART networks, receive inputs UART react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the idle state, the default of which is logic high, (i.e., URXINV = 0). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a start bit detection and will cause the first byte received after the device has been initialized to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin depending on the value of the URXINV bit.
 - a) If URXINV = 0, use a pull-up resistor on the RX pin.
 - b) If URXINV = 1, use a pull-down resistor on the RX pin.
- 2. The first character received on a wake-up from Sleep mode caused by activity on the UxRX pin of the UART module will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock relative to the incoming UxRX bit timing is no longer synchronized, resulting in the first character being invalid. This is to be expected.

18.2 UART Resources

Many useful resources related to UART are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the
	product page using the link above, enter
	this URL in your browser:
	http://www.microchip.com/wwwproducts/
	Devices.aspx?dDocName=en546061

18.2.1 KEY RESOURCES

- Section 17. "UART" (DS70188)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 19-10: CICFG2: ECAN™ MODULE BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	_	:	SEG2PH<2:0>	
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			
bit 7							bit 0	

Legend:								
R = Readable I	oit	W = Writable bit	U = Unimplemented bit, r	ead as '0'				
-n = Value at P	OR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown				
bit 15	Unimplement	ted: Read as '0'						
bit 14	WAKFIL: Sel	ect CAN bus Line Filter for	Wake-up bit					
	1 = Use CAN 0 = CAN bus	bus line filter for wake-up line filter is not used for wak	e-up					
bit 13-11	Unimplement	ted: Read as '0'						
bit 10-8	SEG2PH<2:0	>: Phase Buffer Segment 2	2 bits					
	111 = Length	is 8 x TQ						
	000 = Length	is 1 x TQ						
bit 7	SEG2PHTS:	Phase Segment 2 Time Se	lect bit					
	1 = Freely pro 0 = Maximum	grammable of SEG1PH bits or Informa	tion Processing Time (IPT)	, whichever is greater				
bit 6	SAM: Sample	e of the CAN bus Line bit						
	 1 = Bus line is sampled three times at the sample point 0 = Bus line is sampled once at the sample point 							
bit 5-3	SEG1PH<2:0	>: Phase Buffer Segment 1	bits					
	111 = Length	is 8 x TQ						
	000 = Length	is 1 x TQ						
bit 2-0	PRSEG<2:0>	: Propagation Time Segme	nt bits					
	111 = Length	is 8 x TQ						
	000 = Length	ISTXIQ						

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21.4 Watchdog Timer (WDT)

For PIC24HJXXXGPX06A/X08A/X10A devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler than can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TwDT) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>) which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3,2>) will need to be cleared in software after the device wakes up.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note: If the WINDIS bit (FWDT<6>) is cleared, the CLRWDT instruction should be executed by the application software only during the last 1/4 of the WDT period. This CLRWDT window can be determined by using a timer. If a CLRWDT instruction is executed before this window, a WDT Reset occurs.



FIGURE 21-2: WDT BLOCK DIAGRAM

PIC24HJXXXGPX06A/X08A/X10A

TABLE 22-2:	INSTRUCTION SET OVERVIEW (CONTINUED)
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Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
12	BTST	BTST f,#bit4		Bit Test f	1	1	Z
		BTST.C	TST.C Ws, #bit4 Bit Test Ws to C		1	1	С
		BTST.Z	Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C	Ws,Wb	Bit Test Ws <wb> to C</wb>	1	1	С
		BTST.Z	Ws,Wb	Bit Test Ws <wb> to Z</wb>	1	1	Z
13	BTSTS	BTSTS	f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C	Ws,#bit4	Bit Test Ws to C, then Set	1	1	С
		BTSTS.Z	Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL	lit23	Call subroutine	2	2	None
		CALL	Wn	Call indirect subroutine	1	2	None
15	CLR	CLR	f	f = 0x0000	1	1	None
		CLR	WREG	WREG = 0x0000	1	1	None
		CLR	Ws	Ws = 0x0000	1	1	None
16	CLRWDT	CLRWDT		Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM	f	f = f	1	1	N,Z
		COM	f,WREG	WREG = \overline{f}	1	1	N,Z
		COM	Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP	f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP	Wb,#lit5	Compare Wb with lit5	1	1	C,DC,N,OV,Z
		CP	Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0	f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0	Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB	f	Compare f with WREG, with Borrow		1	C,DC,N,OV,Z
		CPB	Wb,#lit5	Compare Wb with lit5, with Borrow	1	1	C,DC,N,OV,Z
		СРВ	Wb,Ws	Compare Wb with Ws, with Borrow $(Wb - Ws - \overline{C})$	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ	Wb, Wn	Compare Wb with Wn, skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT	Wb, Wn	Compare Wb with Wn, skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT	Wb, Wn	Compare Wb with Wn, skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE	Wb, Wn	Compare Wb with Wn, skip if ≠	1	1 (2 or 3)	None
25	DAW	DAW	Wn	Wn = decimal adjust Wn	1	1	С
26	DEC	DEC	f	f = f - 1	1	1	C,DC,N,OV,Z
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC	Ws,Wd	Wd = Ws - 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2	f	f = f - 2	1	1	C,DC,N,OV,Z
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2	Ws,Wd	Wd = Ws - 2	1	1	C,DC,N,OV,Z
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
31	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	С
32	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	С
33	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	С
34	GOTO	GOTO	Expr	Go to address	2	2	None
		GOTO	Wn	Go to indirect	1	2	None

23.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit™ 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows[®] programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit[™] 2 enables in-circuit debugging on most PIC[®] microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

23.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

23.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

DC CHARACTERISTICS				d Opera otherwing tempe	ting Cone se stated erature -	ditions:) 40°C ≤ 40°C ≤	3.0V to 3.6V TA \leq +85°C for Industrial TA \leq +125°C for Extended
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Мах	Units	Conditions
DI60a	IICL IICH	Input Low Injection Current	0	_	_5 ^(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, and RB11
D160b			0	_	+5 ^(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, RB11, and all 5V tolerant pins ⁽⁷⁾
DI60c	∑ ІІСТ	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁹⁾	_	+20 ⁽⁹⁾	mA	Absolute instantaneous sum of all \pm input injection currents from all I/O pins (IICL + IICH) $\leq \sum$ IICT

TABLE 24-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

- **3:** Negative current is defined as current sourced by the pin.
- 4: See "Pin Diagrams" for a list of 5V tolerant pins.
- **5:** VIL source < (Vss 0.3). Characterized but not tested.
- **6:** Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.
- 7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.
- 8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.
- **9:** Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

PIC24HJXXXGPX06A/X08A/X10A

FIGURE 24-19: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)







DC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for High							
					Temperature						
Param.	Symbol	Characteristic	Min.	Тур.	Max.	Units	Conditions				
		Output Low Voltage I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	_	_	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See Note 1				
HDO10	Vol	Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	_	_	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See Note 1				
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	_	_	0.4	V	Io∟ ≤ 6 mA, Voo = 3.3V See Note 1				
HDO20 Vor		Output High Voltage I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	_	_	V	IoL ≥ -1.8 mA, VDD = 3.3V See Note 1				
	Vон	Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	_	_	V	Io∟ ≥ -3 mA, VDD = 3.3V See Note 1				
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	_	_	V	Io∟ ≥ -6 mA, VDD = 3.3V See Note 1				
		Output High Voltage I/O Pins:	1.5	—	—		IOH ≥ -1.9 mA, VDD = 3.3V See Note 1				
		2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.0	_		V	IOH ≥ -1.85 mA, VDD = 3.3V See Note 1				
			3.0	_	_		$\label{eq:IOH} \begin{array}{l} \text{IOH} \geq -1.4 \text{ mA, VDD} = 3.3 \text{V} \\ \text{See Note 1} \end{array}$				
		Output High Voltage 4x Source Driver Pins - RA2, RA3,	1.5	_			IOH ≥ -3.9 mA, VDD = 3.3V See Note 1				
HDO20A	Voн1	RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.0	—	_	V	IOH ≥ -3.7 mA, VDD = 3.3V See Note 1				
			3.0	_	_		IOH ≥ -2 mA, VDD = 3.3V See Note 1				
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO,	1.5	_			IOH ≥ -7.5 mA, VDD = 3.3V See Note 1				
		IRC15	2.0	_		V	IOH ≥ -6.8 mA, VDD = 3.3V See Note 1				
			3.0	—	_		IOH ≥ -3 mA, VDD = 3.3V See Note 1				

TABLE 25-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

Note 1: Parameters are characterized, but not tested.

TABLE 25-14: ADC MODULE SPECIFICATIONS

/ CHARAC	AC TERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$ for High Temperature						
Param No. Symbol		Characteristic M		Тур	Max	Units	Conditions	
Reference Inputs								
HAD08	IREF	Current Drain	_	250 —	600 50	μΑ μΑ	ADC operating, See Note 1 ADC off, See Note 1	

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 25-15: ADC MODULE SPECIFICATIONS (12-BIT MODE)⁽³⁾

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$ for High Temperature									
Param No.	Symbol	Characteristic	Min	Тур	Мах	Units	Conditions				
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF- ⁽¹⁾											
AD23a	Gerr	Gain Error		5	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V				
AD24a	EOFF	Offset Error	_	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V				
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF- ⁽¹⁾											
AD23a	Gerr	Gain Error	2	10	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD24a	Eoff	Offset Error	2	5	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
Dynamic Performance (12-bit Mode) ⁽²⁾											
HAD33a	Fnyq	Input Signal Bandwidth	—		200	kHz	—				

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

TABLE 25-16: ADC MODULE SPECIFICATIONS (10-BIT MODE)⁽³⁾

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$ for High Temperature									
Param No.	Symbol	Characteristic	Min	Тур	Мах	Units	Conditions				
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF- ⁽¹⁾											
AD23b	Gerr	Gain Error		3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V				
AD24b	EOFF	Offset Error	-	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V				
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF- ⁽¹⁾											
AD23b	Gerr	Gain Error	—	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
AD24b	EOFF	Offset Error	-	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V				
Dynamic Performance (10-bit Mode) ⁽²⁾											
HAD33b	Fnyq	Input Signal Bandwidth	—	_	400	kHz	_				

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Chamfers at corners are optional; size may vary.

Lead Thickness

Lead Width

Molded Package Width

Molded Package Length

Mold Draft Angle Top

Mold Draft Angle Bottom

3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.

E1

D1

С

b

α

β

0.09

0.17

11°

11°

10.00 BSC

10.00 BSC

0.22

12°

12°

4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

0.20

0.27

13°

13°